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L3: Entry 2 of 2

File: DWPI

Jan 16, 1998

DERWENT-ACC-NO: 1998-136392

DERWENT-WEEK: 199814

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TITLE: Substrate processing apparatus e.g. for glass substrate or semiconductor wafer - has first vapour-liquid separation part coupled to first ejection path, to isolate first process liquid which is then fed to process liquid reservoir part

PATENT-ASSIGNEE:

ASSIGNEE

CODE

DAINIPPON SCREEN SEIZO KK

DNIS

PRIORITY-DATA: 1996JP-0161548 (June 21, 1996)

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PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
<input type="checkbox"/> JP 10012523 A	January 16, 1998		011	H01L021/027

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
JP 10012523A	June 21, 1996	1996JP-0161548	

INT-CL (IPC): G03F 7/30; H01L 21/027; H01L 21/304; H01L 21/306

ABSTRACTED-PUB-NO: JP 10012523A

BASIC-ABSTRACT:

The apparatus has a process liquid reservoir part which stores first process liquid. A first process liquid supply part supplies first process liquid from reservoir part to a substrate (W). A second process liquid supply part supplies a second process liquid onto the substrate. A collection part collects process liquid from the substrate. A switching valve (70) is provided which makes a first ejection path to discharge collected first process liquid, and a second ejection path to discharge collected second process liquid. A first vapour-liquid separation part which is coupled to the first ejection path, isolates the first process liquid which is fed back to process liquid reservoir part. Similarly, a second vapour-liquid separation part which is coupled to second ejection path, isolates the second process liquid and passed to an exhaust line.

USE - In LCD device manufacture.

ADVANTAGE - Prevents contamination of substrate by de- spreading of process liquid

mist. Reduces wastage of process liquid. Reduces cost of apparatus by assembling collection part and process tank.

CHOSEN-DRAWING: Dwg.1/9

TITLE-TERMS: SUBSTRATE PROCESS APPARATUS GLASS SUBSTRATE SEMICONDUCTOR WAFER FIRST
VAPOUR LIQUID SEPARATE PART COUPLE FIRST EJECT PATH ISOLATE FIRST PROCESS LIQUID
FEED PROCESS LIQUID RESERVOIR PART

DERWENT-CLASS: L03 P84 U11

CPI-CODES: L03-G05A; L04-D;

EPI-CODES: U11-C04; U11-C06A1; U11-C06A1B; U11-C07;

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C1998-044617

Non-CPI Secondary Accession Numbers: N1998-108216

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L2: Entry 1 of 1

File: DWPI

May 5, 2005

DERWENT-ACC-NO: 2005-314313

DERWENT-WEEK: 200532

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TITLE: Substrate processing apparatus for etching and cleaning substrate e.g. semiconductor wafer, has processing liquid supply unit which leads processing liquid onto peripheral portion of substrate which rotates and holds substrate holder

INVENTOR: ITO, K ; KAMEZAWA, M ; SAITO, T ; SUZUKI, T ; YAMADA, K ; YAMAGUCHI, K

PATENT-ASSIGNEE:

ASSIGNEE	CODE
ITO K	ITOKI
KAMEZAWA M	KAMEI
SAITO T	SAITI
SUZUKI T	SUZUI
YAMADA K	YAMAI
YAMAGUCHI K	YAMAI

PRIORITY-DATA: 2003US-0695826 (October 30, 2003)

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PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
<input type="checkbox"/> US 20050092351 A1	May 5, 2005		022	B08B003/02

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
US20050092351A1	October 30, 2003	2003US-0695826	

INT-CL (IPC): B08B 3/02

ABSTRACTED-PUB-NO: US20050092351A

BASIC-ABSTRACT:

NOVELTY - The apparatus has a substrate holder e.g. vacuum chuck (11) which rotates and holds the substrate (W) at a horizontal position, and a processing liquid supply unit which leads processing liquid onto the peripheral portion of the substrate. The substrate is rotated while the processing liquid is kept stationary relative to the substrate.

DETAILED DESCRIPTION - An INDEPENDENT CLAIM is also included for a substrate etching method.

USE - For etching thin film at peripheral portion of substrate e.g. semiconductor wafer, and cleaning substrate after etching process.

ADVANTAGE - Ensures reliable supply of processing liquid onto substrate while suppressing scattering of liquid, such that clean atmosphere in chamber is maintained and reducing usage of processing liquid.

DESCRIPTION OF DRAWING(S) - The figure shows the sectional view of the substrate processing apparatus.

Chamber 1

Chamber body 1a

Chamber cover 2

Upper shaft 6

Substrate holder e.g. vacuum chuck 11

Substrate W

CHOSEN-DRAWING: Dwg.1/14

TITLE-TERMS: SUBSTRATE PROCESS APPARATUS ETCH CLEAN SUBSTRATE SEMICONDUCTOR WAFER
PROCESS LIQUID SUPPLY UNIT LEAD PROCESS LIQUID PERIPHERAL PORTION SUBSTRATE
ROTATING HOLD SUBSTRATE HOLD

DERWENT-CLASS: P43

SECONDARY-ACC-NO:

Non-CPI Secondary Accession Numbers: N2005-256919

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WEST Search History

DATE: Tuesday, January 02, 2007

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<input type="checkbox"/>	L1	10695826	0

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purge

2 entries found for **purge**.

To select an entry, click on it.

purge[1,verb]
purge[2,noun]

Go

Main Entry: **¹purge**

Pronunciation: 'pärj

Function: *verb*

Inflected Form(s): **purged**; **purg-ing**

Etymology: Middle English, from Anglo-French *purger*, from Latin *purigare*, *purgare* to purify, purge, from *purus* pure + *-igare* (akin to *agere* to drive, do) -- more at [ACT](#)

transitive verb

1 a : to clear of guilt **b** : to free from moral or ceremonial defilement

2 a : to cause evacuation from (as the bowels) **b** (1) : to make free of something unwanted <*purge* a manhole of gas> <*purge* yourself of fear> (2) : to free (as a boiler) of sediment or relieve (as a steam pipe) of trapped air by bleeding **c** (1) : to rid (as a nation or party) by a purge (2) : to get rid of <the leaders had been *purged*>

intransitive verb

1 : to become **purged**

2 : to have or produce frequent evacuations

3 : to cause **purgation**

- **purg-er** *noun*

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Pronunciation Symbols



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Key: "S:" = Show Synset (semantic) relations, "W:" = Show Word (lexical) relations

Noun

- S: (n) **purge**, purging, purgation (the act of clearing yourself (or another) from some stigma or charge)
- S: (n) **purge**, purging (an act of removing by cleansing; ridding of sediment or other undesired elements)

Verb

- S: (v) **purge** (oust politically) *"Deng Xiao Ping was purged several times throughout his lifetime"*
- S: (v) **purge** (clear of a charge)
- S: (v) purify, **purge**, sanctify (make pure or free from sin or guilt) *"he left the monastery purified"*
- S: (v) **purge** (rid of impurities) *"purge the water"; "purge your mind"*
- S: (v) flush, scour, **purge** (rinse, clean, or empty with a liquid) *"flush the wound with antibiotics"; "purge the old gas tank"*
- S: (v) vomit, vomit up, **purge**, cast, sick, cat, be sick, disgorge, regorge, retch, puke, barf, spew, spue, chuck, upchuck, honk, regurgitate, throw up (eject the contents of the stomach through the mouth) *"After drinking too much, the students vomited"; "He purged continuously"; "The patient regurgitated the food we gave him last night"*
- S: (v) **purge** (excrete or evacuate (someone's bowels or body)) *"The doctor decided that the patient must be purged"*

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